

ABSTRACT

A semiconductor package comprises a semiconductor chip provided with a plurality of electric terminals, a plurality of electrically conductive members electrically connected with the electric terminals, respectively, a connection terminal spherical in shape, made of solder, electrically connected with each of the electrically conductive members, corresponding thereto, and a sealing member for sealing a semiconductor chip and the electrically conductive members, and for covering the connection terminals so as to allow a part thereof to be exposed.

The electrically conductive members are provided with a bonding promoter for promoting bonding thereof by solder with the connection terminal spherical in shape, and are connected with the respective connection terminals spherical in shape, corresponding thereto, at the respective bonding promoters.